

## Thermal RC network (Foster)

## **SPICE thermal model**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base		-	-	0.57	K/W
	Cth <sub>1</sub>	1.835E-04 F		<del>个</del>	tj	
	Cth <sub>2</sub>	1.308E-03 F		<b>↓</b>	<u>, 1</u>	
	Cth <sub>3</sub>	9.881E-04 F			<u> </u>	
	Cth <sub>4</sub>	3.804E-03 F				1
	Cth <sub>5</sub>	1.211E-02 F		L L		•
	Cth <sub>6</sub>	2.411E-02 F				
	Cth <sub>7</sub>	5.977E-01 F		ſ	<b>h i</b>	
	Cth <sub>8</sub>	1.623E+02 F			$\int Rth_2 + Cth_2$	2
	Rth₁	4.855E-04 Ω				
	Rth <sub>2</sub>	9.542E-04 Ω		r	<b>-</b>	
	Rth <sub>3</sub>	1.131E-02 Ω			Rth3 = Cth	3
	Rth <sub>4</sub>	2.702E-02 Ω		L	᠊ᢩ᠆᠆᠆	
	Rth₅	9.606E-02 Ω				
	Rth <sub>6</sub>	3.569E-01 Ω			Rth4 📥 Cth	4
	Rth <sub>7</sub>	8.813E-02 Ω		L l	<b></b>	4
	Rth <sub>8</sub>	1.348Ε-03 Ω	(	Р		
						5
						6
						7
'art:	BUK962R6-40E					B
ate:	11/4/2013				└ <b>─</b> ╋──┘	
Nodel Rth	0.58 K/W			↓ ↓	 t <sub>amb</sub> 001aal76	

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